|  |  |
| --- | --- |
| A picture containing electronics, computer, photo  Description automatically generated  (a) | A picture containing outdoor, building, photo, side  Description automatically generated  (b) |
| A picture containing photo, sitting, person, brick  Description automatically generated  (c) | A close up of a person  Description automatically generated  (d) |
| A picture containing indoor, photo, sitting, table  Description automatically generated  (e) | Diagram  Description automatically generated  (f) |
| A picture containing text, monitor, black, nature  Description automatically generated  (g) | A picture containing graphical user interface  Description automatically generated  (h) |

Suppl. Figure 2. APT sample preparation for McLaughlin sample, showing liftout process and typical sample sharpening using Xe plasma FIB. Images show the following: (a) Liftout location, (b) protective W deposition, (c) trench cuts around ROI, (d) cantilever sample prior to liftout, (e) extraction using micro-manipulator, (f) sample mounted on Si micropost, (g) sample during annular milling, (h) sample after final sharpening.